



GaN HEMT 50V, 330W, 1.5GHz RF Power Transistor

Description

The SC3033RVS is a 330W, single ended GaN HEMT, designed for multiple applications with Frequencies up to 1.5GHz. It is optimized thermally to better support wideband CW or wider pulse or higher duty cycle application.

There is no guarantee of performance when this part is used in applications designed outside of these frequencies.

It is the thermal enhancement of SL2033VS and SU1532V.

SC3033RVS



- Typical RF performance on 0.7-1.3GHz wideband application board with device soldered under higher duty cycle

SC3033RVS ^{V2} V _{gs} =-3.24V V _{ds} =50V Id _q =120mA Pulse 300us 50%						
Freq (MHz)	Psat (dBm)	Psat (W)	IDS (A)	Pin (dBm)	Gain (dB)	Eff (%)
700	54.93	311.2	5.96	37.65	17.28	52.21
750	54.93	311.2	5.74	37.70	17.23	54.21
800	55.48	353.2	5.82	38.08	17.40	60.68
850	55.69	370.7	5.69	39.04	16.65	65.15
900	54.95	312.6	4.75	39.06	15.89	65.81
950	54.81	302.7	6.05	39.37	15.44	50.03
1000	55.77	377.6	6.61	40.47	15.30	57.12
1050	55.79	379.3	6.16	38.42	17.37	61.58
1100	55.91	389.9	5.62	38.61	17.30	69.38
1150	55.67	369.0	5.00	38.40	17.27	73.80
1200	55.27	336.5	4.39	39.33	15.94	76.65
1224	55.02	317.7	4.21	40.84	14.18	75.46

- Typical RF performance on 0.5-1GHz wideband application board with device soldered under CW

SC3033RVS ^{V2} V _{gs} =-3.24V V _{ds} =50V Id _q =120mA CW						
Freq (MHz)	Psat (dBm)	Psat (W)	IDS (A)	Pin (dBm)	Gain (dB)	Eff (%)
450	53.88	244.34	8.43	41.94	11.94	57.97
500	54.58	287.08	9.12	42.62	11.96	62.96
550	54.2	263.03	8	41.58	12.62	65.76
600	54.41	276.06	7.96	42.47	11.94	69.36
650	53.89	244.91	7.17	41.96	11.93	68.31
700	53.64	231.21	6.85	41	12.64	67.51
750	53.56	226.99	7.38	41.08	12.48	61.51



800	53.76	237.68	7.91	41.1	12.66	60.10
850	53.75	237.14	8.53	40.72	13.03	55.60
900	53.64	231.21	8.89	40.34	13.3	52.01
950	53.28	212.81	8.3	39.4	13.88	51.28
1000	54.09	256.45	8.57	39.44	14.65	59.85

Applications

- L band power amplifier application
- P band power amplifier application
- S band power amplifier application

Important Note: Proper Biasing Sequence for GaN HEMT Transistors

Turning the device ON

1. Set VGS to the pinch--off (VP) voltage, typically -5 V
2. Turn on VDS to nominal supply voltage
3. Increase VGS until IDS current is attained
4. Apply RF input power to desired level

Turning the device OFF

1. Turn RF power off
2. Reduce VGS down to VP, typically -5 V
3. Reduce VDS down to 0 V
4. Turn off VGS

Table 1. Maximum Ratings

Rating	Symbol	Value	Unit
Drain--Source Voltage	V_{DSS}	+200	Vdc
Gate--Source Voltage	V_{GS}	-8 to +0.5	Vdc
Operating Voltage	V_{DD}	55	Vdc
Maximum gate current	I_{GS}	43.2	mA
Storage Temperature Range	T_{stg}	-65 to +150	°C
Case Operating Temperature	T_C	+150	°C
Operating Junction Temperature	T_J	+225	°C

Table 2. Thermal Characteristics

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction to Case by FEA $T_C = 85^\circ\text{C}$, at $P_d = 150\text{W}$,	$R_{\theta JC}$	0.55	°C /W

Table 3. Electrical Characteristics (TA = 25°C unless otherwise noted)

DC Characteristics

Characteristic	Conditions	Symbol	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	$V_{GS} = -8\text{V}$; $I_{DS} = 43.2\text{mA}$	V_{DSS}		200		V
Gate Threshold Voltage	$V_{DS} = 10\text{V}$, $I_D = 43.2\text{mA}$	$V_{GS(th)}$	-4		-2	V
Gate Quiescent Voltage	$V_{DS} = 50\text{V}$, $I_{DS} = 100\text{mA}$, Measured in Functional Test	$V_{GS(Q)}$		-3.2		V

Ruggedness Characteristics

Characteristic	Conditions	Symbol	Min	Typ	Max	Unit
Load mismatch capability	50V 2GHz, $P_{out} = 330\text{W}$ pulsed CW, All phase, No device damages	VSWR		10:1		



0.7-1.3GHz

Figure 1. Network Analyzer result S11 and S21 VDS= 50V, IDQ = 500mA

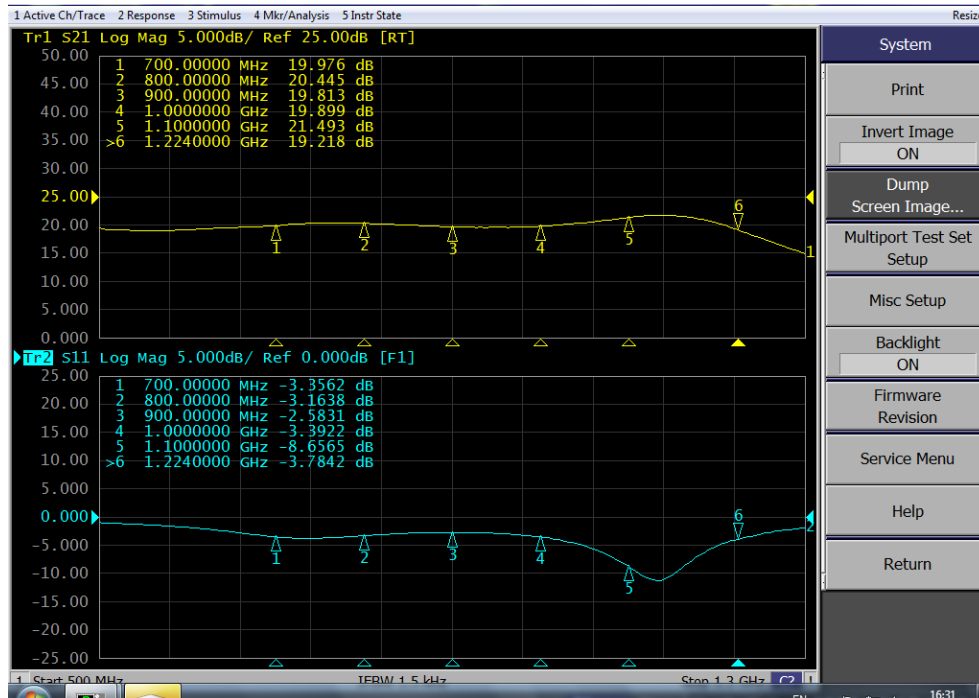


Figure 2: Picture of application board for 700-1224MHz Class AB

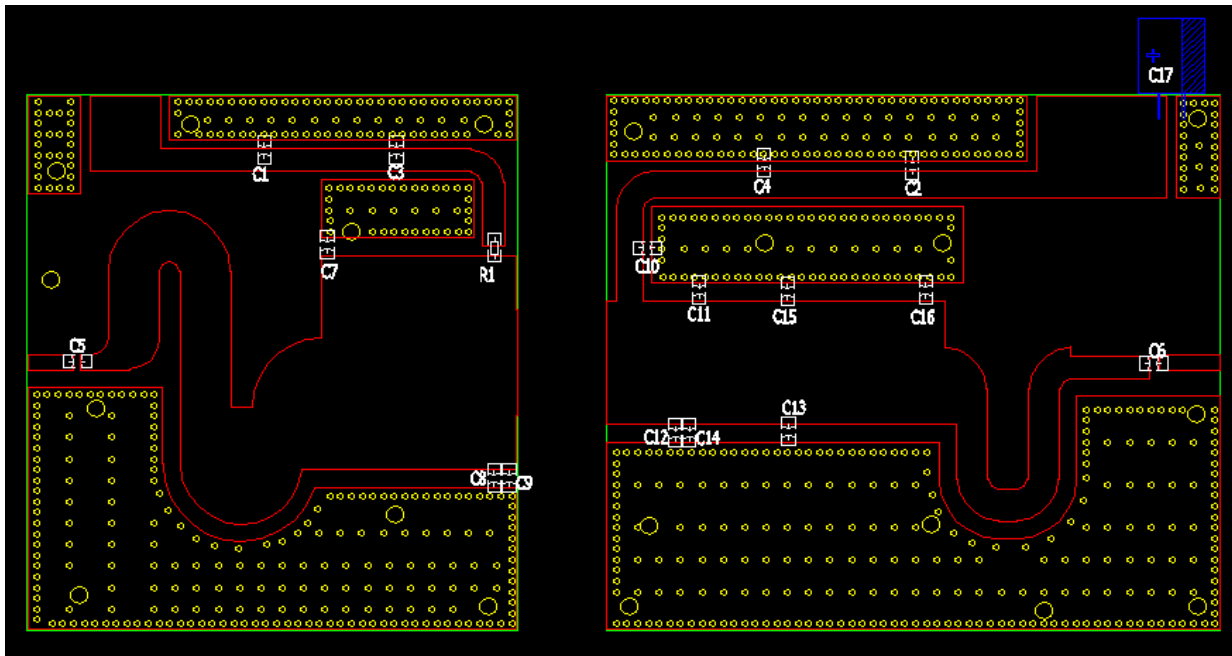


Table 4. Bill of materials of application board (PCB layout upon request)

Component	Description	Suggestion
C1,C2	10uF	10uF/100V
C3,C4	100pF	MQ101111
C5,C6	47pF	MQ101111



C17	1000uF/63V	Electrolytic Capacitor
R1	18 Ω	Chip Resistor
C7	4.7pF	MQ101111
C8	2pF	MQ101111
C9	5.1pF	MQ101111
C10	3.6pF	MQ101111
C11	3.0pF	MQ101111
C12,C13	1.8pF	MQ101111
C14	2.2pF	MQ101111
C15	2.7pF	MQ101111
C16	1pF	MQ101111
PCB	30mil Rogers 4350B	

0.5-1GHz

Figure 3. Network Analyzer result S11 and S21 VDS= 50V, IDQ = 500mA

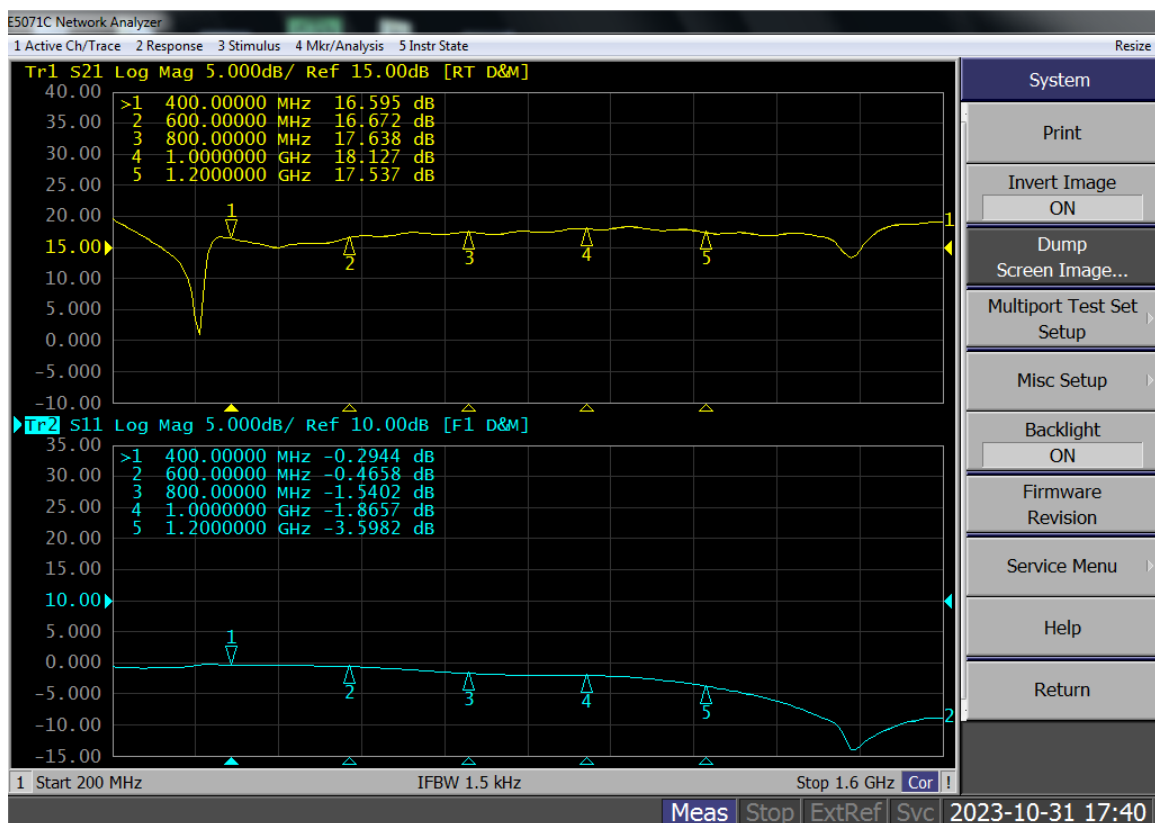


Figure 4: Picture of application board for 500-1000MHz Class AB

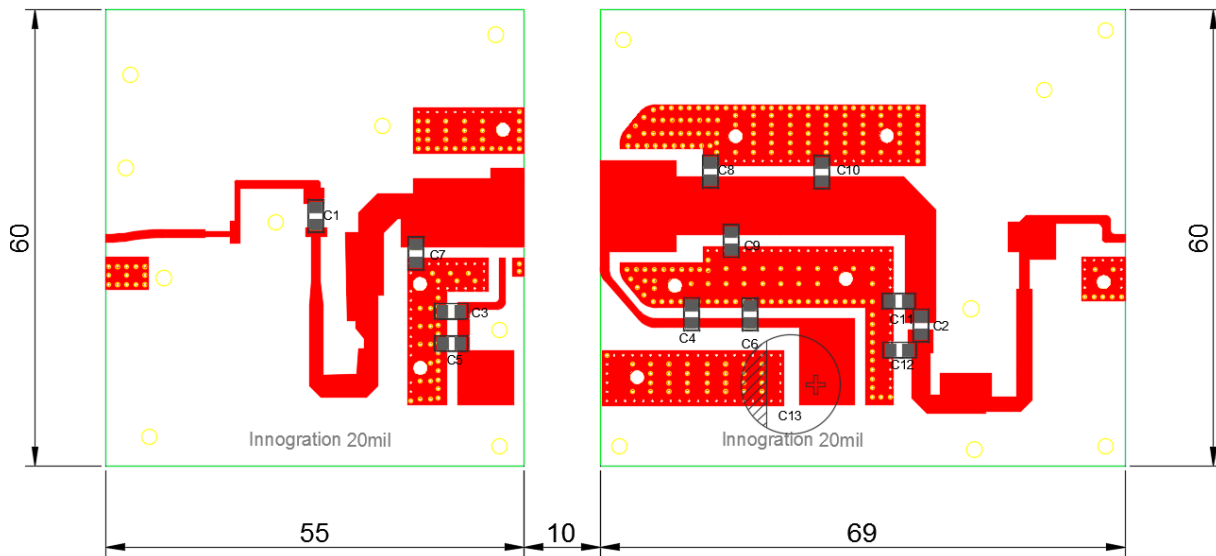


Table 5. Bill of materials of application board (PCB layout upon request)

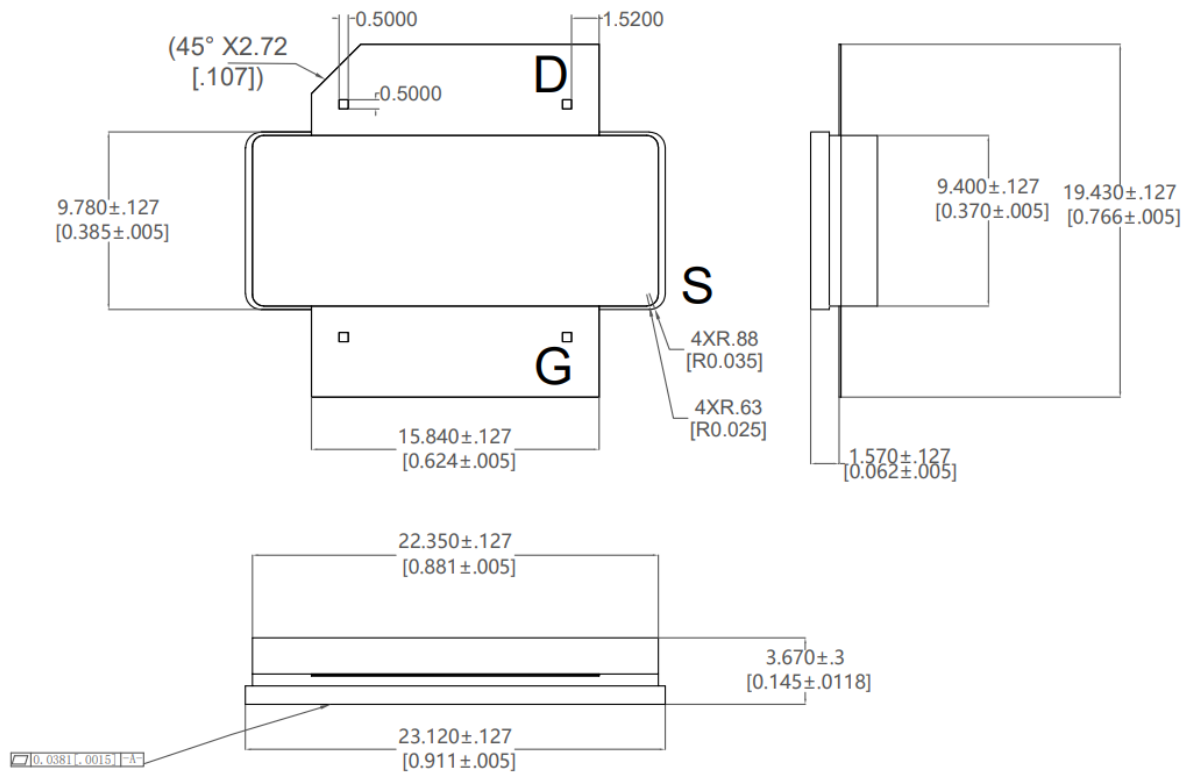
Component	Description	Suggestion
C1~C4	82pF	MQ101111
C5,C6	10uF	Ceramic multilayer capacitor
C7,C10	3.3pF	MQ301111
C8	3pF	MQ301111
C9	2.2pF	MQ301111
C11	2.4pF	MQ301111
C12	1.0pF	MQ301111
C13	1000uF/63V	Electrolytic Capacitor
R1	10 Ω 1206	Chip Resistor
PCB	20Mil Rogers4350	



Package Outline

Flangeless ceramic package;

INP-688-2-EL (C2)



OUTLINE VERSION	REFERENCE			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
PKG-C2					09/27/2018



Revision history

Table 4. Document revision history

Date	Revision	Datasheet Status
2023/5/14	V1.0	Production Datasheet Creation
2023/9/12	V1.1	Change carrier application to 0.7-1.3GHz data and indicate 1-2G data
2023/10/31	V1.2	Add 0.5-1GHz application data
2026/1/1	V2.0	Modify the upper limits from 3GHz to 1.5GHz, >1.5GHz supported by newer and better part STBV27W350RC2

Application data based on HL-23-21/HL-23-36/TC-23-58/HL-23-52

Notice

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